

**8821 Dual N-Channel MOSFET**

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$ Max
19V	0.007Ω @ 4.5V	15A
	0.009Ω @ 2.5V	

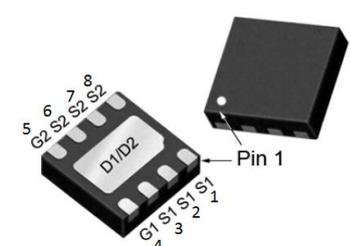
**FEATURE**

- TrenchFET Power MOSFET
- Excellent  $R_{DS(on)}$
- Low Gate Charge
- High Power and Current Handling Capability
- Surface Mount Package
- ESD Rating:2000V HBM

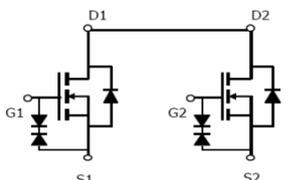
**APPLICATION**

- Battery Protection
- Load Switch
- Power Management

**DFN-3x3-8L**



**Equivalent Circuit**



**MARKING**

8821

TFXYWC

Y :year code W :week code

**ABSOLUTE MAXIMUM RATINGS ( $T_a=25^{\circ}C$  unless otherwise noted)**

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	19	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Continuous Drain Current	$I_D$	15	A
Pulsed Drain Current (note 1)	$I_{DM}$	45	A
Thermal Resistance from Junction to Ambient (note 2)	$R_{\theta JA}$	38	$^{\circ}C/W$
Junction Temperature	$T_J$	150	$^{\circ}C$
Storage Temperature	$T_{STG}$	-55~+150	$^{\circ}C$
Lead Temperature for Soldering Purposes(1/8" from case for 10 s)	$T_L$	260	$^{\circ}C$



**MOSFET ELECTRICAL CHARACTERISTICS**

Ta =25 °C unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>STATIC CHARACTERISTICS</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	19			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 19V, V_{GS} = 0V$			1	$\mu A$
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 12V, V_{DS} = 0V$			$\pm 7$	$\mu A$
Gate threshold voltage (note 3)	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	0.5	0.6	1.0	V
Drain-source on-resistance (note 3)	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 8.0A$	4.5	5.5	7.0	$m\Omega$
		$V_{GS} = 3.5V, I_D = 7.0A$	5.5	6.0	8.0	$m\Omega$
		$V_{GS} = 2.5V, I_D = 6.0A$	6.5	7.0	9.0	$m\Omega$
Forward transconductance (note 3)	$g_{FS}$	$V_{DS} = 5V, I_D = 4A$		10		S
Diode forward voltage (note 3)	$V_{SD}$	$I_S = 1.50A, V_{GS} = 0V$			1.0	V
<b>DYNAMIC CHARACTERISTICS (note4)</b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 10V, V_{GS} = 0V, f = 1MHz$		879		$\mu F$
Output Capacitance	$C_{oss}$			245		$\mu F$
Reverse Transfer Capacitance	$C_{rss}$			232		$\mu F$
<b>SWITCHING CHARACTERISTICS (note 4)</b>						
Turn-on delay time	$t_{d(on)}$	$V_{GS} = 4.5V, V_{DS} = 10V, I_D = 6A$ $R_{GEN} = 3\Omega$		6.2		ns
Turn-on rise time	$t_r$			15		ns
Turn-off delay time	$t_{d(off)}$			42		ns
Turn-off fall time	$t_f$			13		ns
Total Gate Charge	$Q_g$	$V_{DS} = 10V, V_{GS} = 4.5V, I_D = 6A$		16		nC
Gate-Source Charge	$Q_{gs}$			3.2		nC
Gate-Drain Charge	$Q_{gd}$			5.0		nC

**Notes :**

- 1.Repetitive rating: Pluse width limited by maximum junction temperature
- 2.Surface Mounted on FR4 board,  $t \leq 10$  sec.
3. Pulse test : Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

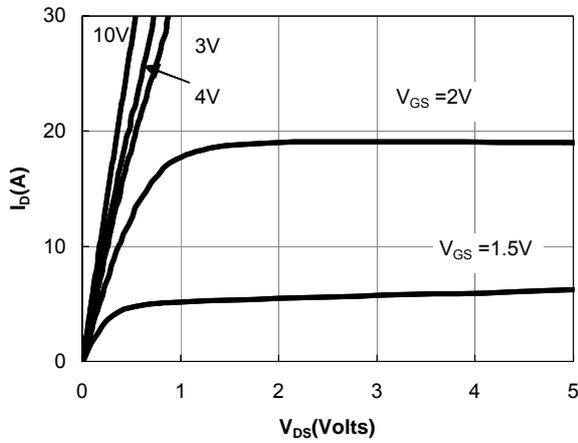


Figure 1: On-Regions Characteristic CS

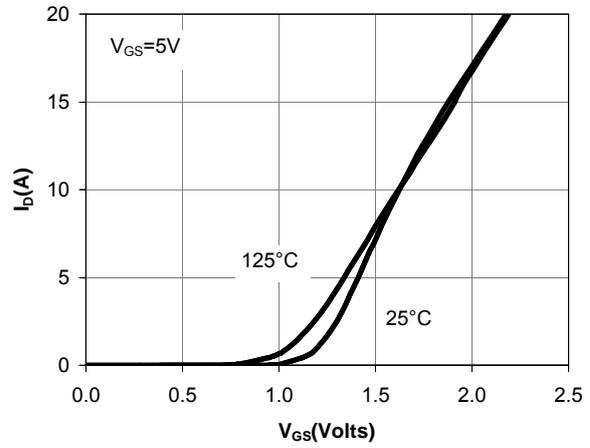


Figure 2: Transfer Characteristics

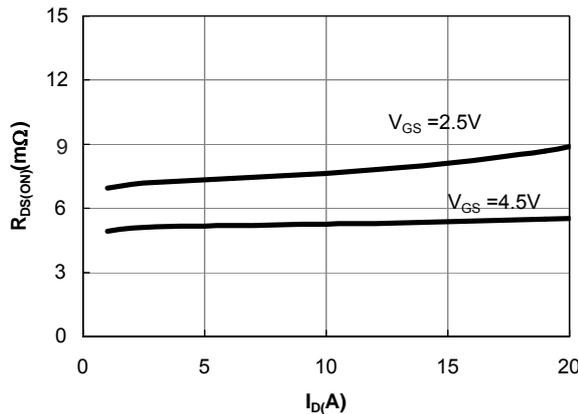


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

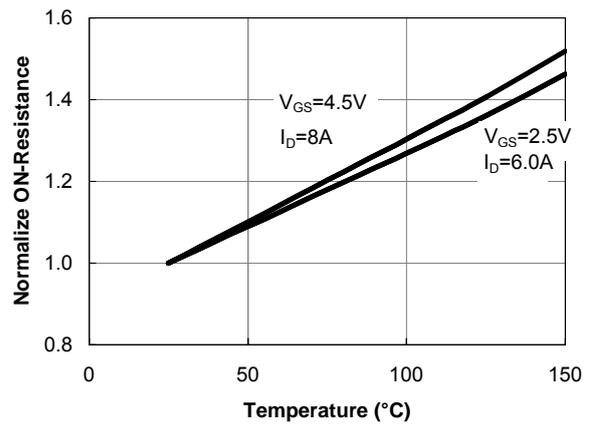


Figure 4: On-Resistance vs. Junction Temperature

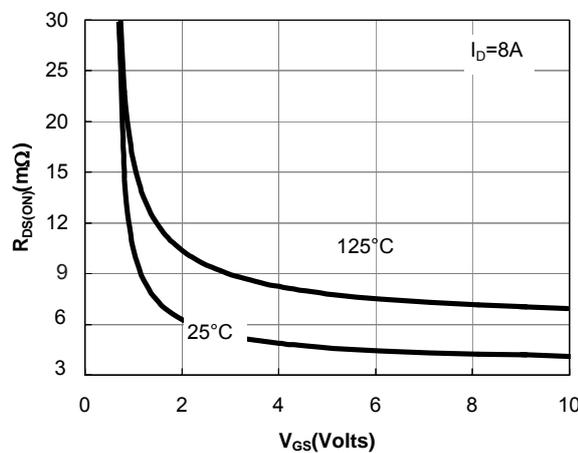


Figure 5: On-Resistance vs. Gate-Source Voltage

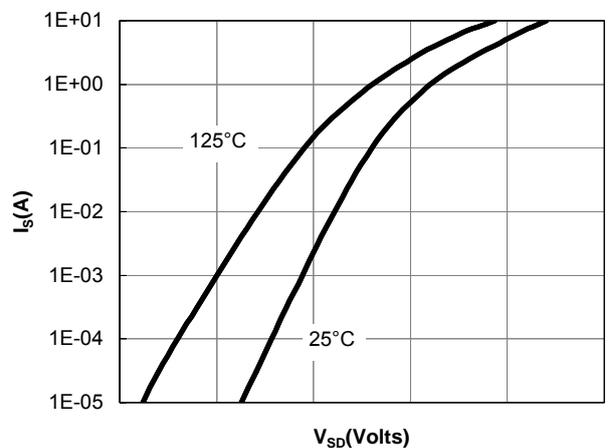


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

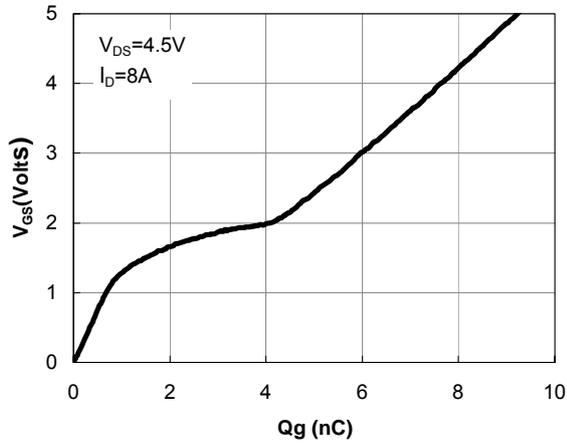


Figure 7: Gate-Charge Characteristics

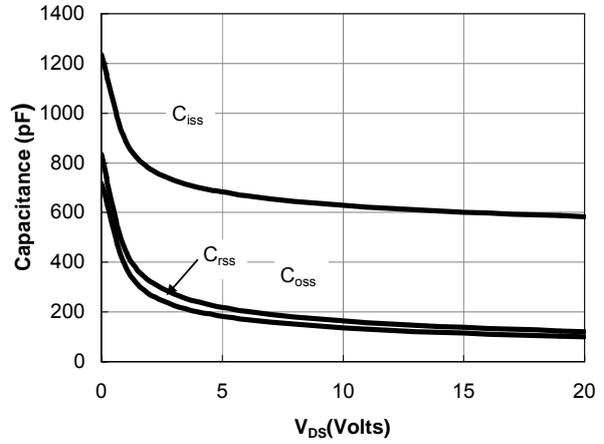


Figure 8: Capacitance Characteristics

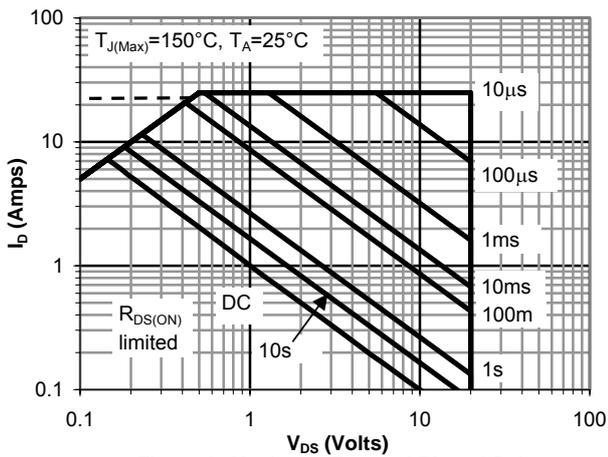


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

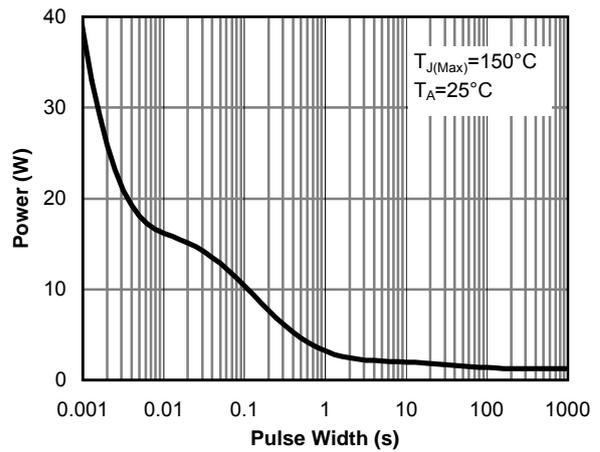


Figure 10: Single Pulse Power Rating Junction-to-

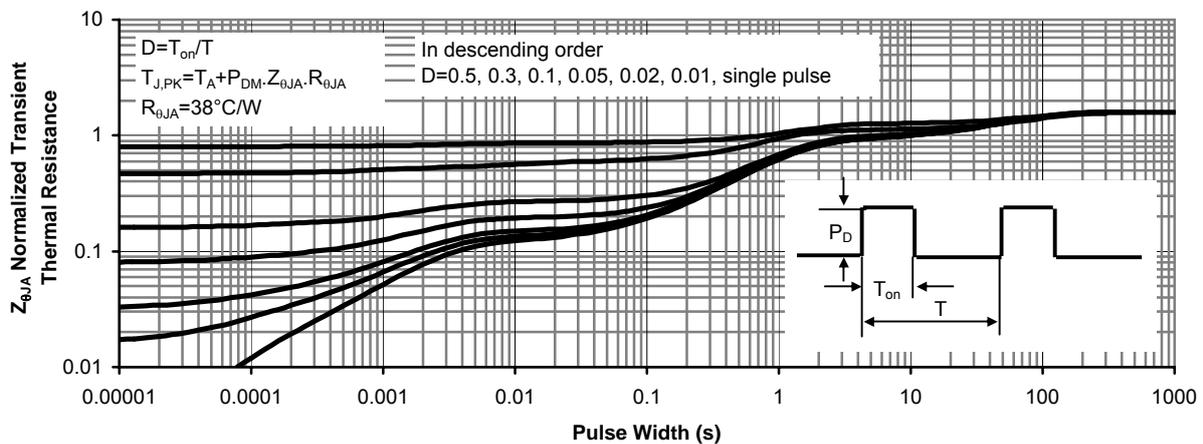
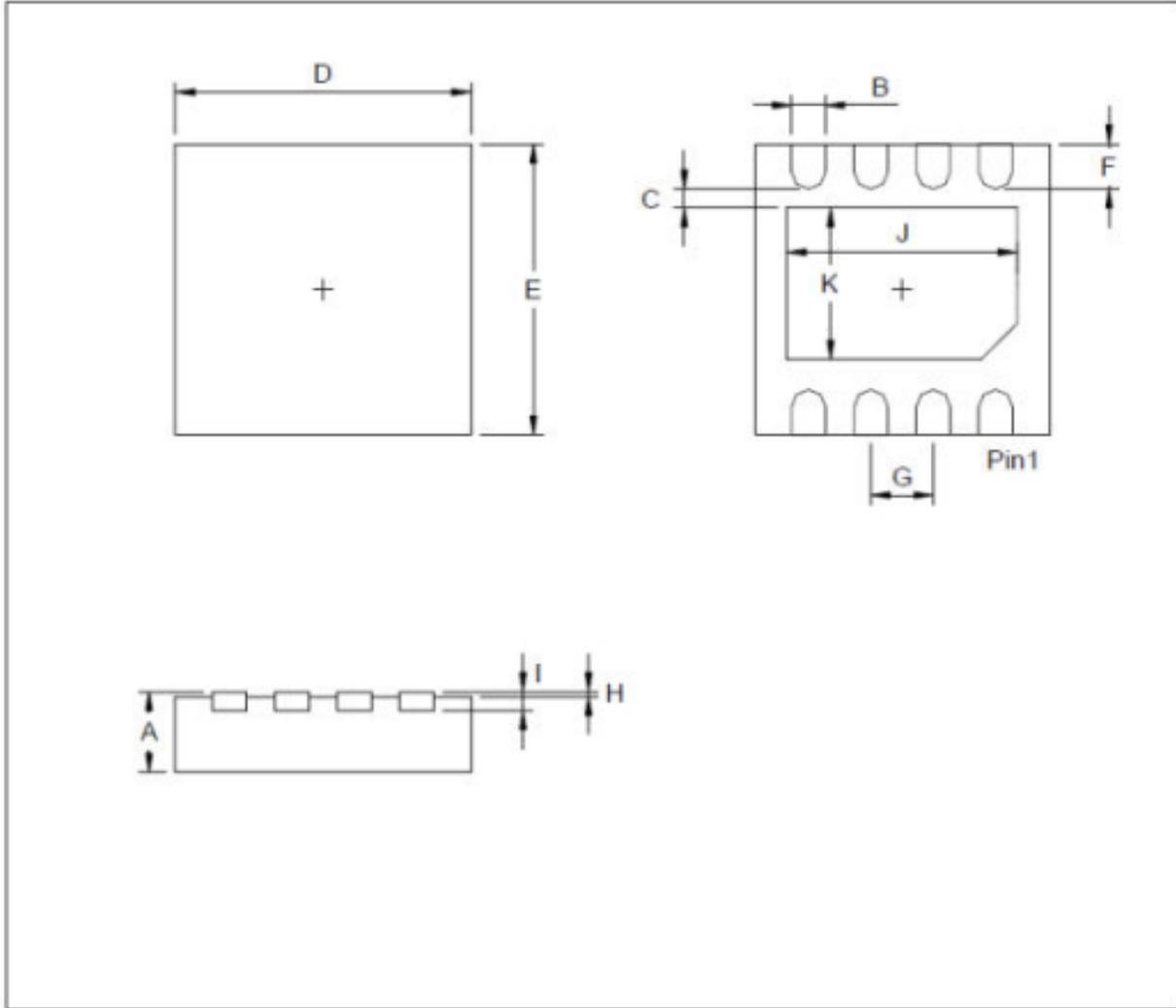


Figure 11: Normalized Maximum Transient Thermal Impedance

PDFN3×3 Package Outline Data



Dimension	mm			Dimension	mm		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	0.7		0.8	I		0.203	
B	0.25		0.35	J	2.2		2.4
C	0.2			K	1.4		1.6
D	2.924		3.076				
E	2.924		3.076				
F	0.324		0.476				
G		0.65					
H	0		0.05				